MSKSEMI 美森科













ESD

TVS

TSS

MOV

GDT

PLED

AZ5825-01F-MS

Product specification





FEATURES

- ESD per IEC 61000-4-2 ±30 kV (Contact)
- ESD per IEC 61000-4-2 ±30 kV (Air)
- IEC61000-4-4 (EFT) 40A (5/50ns)
- Peak power dissipation: 400W (8/20µs)
- Protects one Vcc or data line
- Low clamping voltage
- Working voltages : 5V
- Low leakage current
- Low capacitance

MACHANICAL DATA

- DFN100-2L package
- Flammability Rating: UL 94V-0
- High temperature soldering guaranteed: 260 C/10s
- Packaging: Tape and Reel
- Reel size: 7 inch

APPLICATIONS

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Networking and Telecom
- Serial and Parallel Ports
- Peripherals

Reference News

PACKAGE OUTLINE	PIN CONFIGURATION	Marking
		H
DFN1006-2L		



ABSOLUTE MAXIMUM RATING

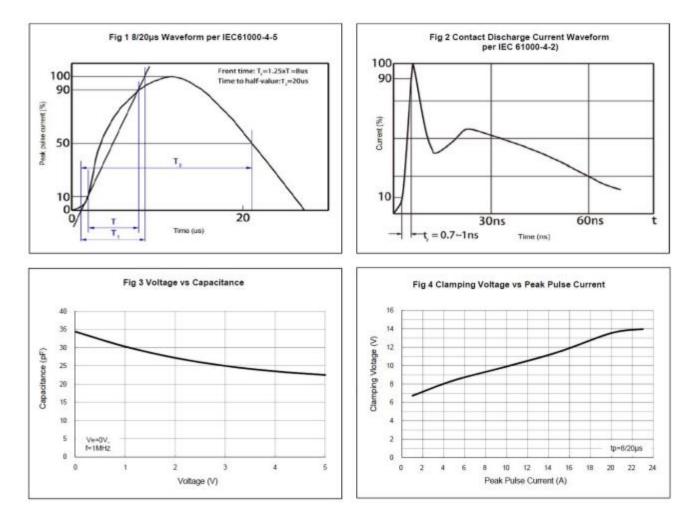
Symbol	Parameter	Value	Units
	ESD per IEC 61000-4-2 (Contact)	±30	177
VESD	ESD per IEC 61000-4-2 (Air)	±30	κV
Ррр	Peak Pulse Power (8/20µs)	400	W
ТОРТ	Operating Temperature	-55~150	OC
TSTG	Storage Temperature	-55~150	OC

ELECTRICAL CHARACTERISTICS (Tamb=25 °C)

Symbol	Parameter	Test Condition	Min	Тур	Max	Units
VRWM	Reverse Working Voltage				5.0	v
VBR	Reverse Breakdown Voltage	IT = 1mA	5.8		9.0	v
IR	Reverse Leakage Current	VRWM = 5V			1.0	μΑ
VC	Clamping Voltage	IPP = 1A, tp = 8/20µs			9.8	V
VC	Clamping Voltage	IPP = 20A, tp = 8/20µs		15	20	V
CJ	Junction Capacitance	V _R = 0V, f = 1MHz		33	40	pF

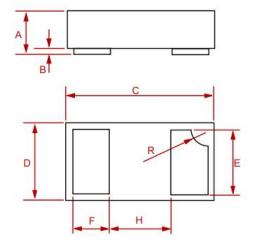


ELECTRICAL CHARACTERISTICS CURVE



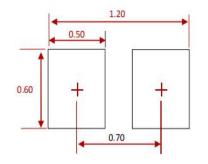


PACKAGE MECHANICAL DATA



Dim	Inches		Millimeters	
	MIN	МАХ	MIN	МАХ
А	0.0125	0.02	0.32	0.52
В	0.000	0.002	0.00	0.05
с	0.037	0.043	0.95	1.080
D	0.022	0.027	0.55	0.680
E	0.016	0.024	0.40	0.60
F	0.008	0.012	0.20	0.30
н	0.01	5Тур.	0.40	Тур.
R	0.001	0.005	0.05	0. 15

Suggested Pad Layout



NOTES:

- 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
- 2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT Y OUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFAC TURING GUIDELINES ARE MET.

REEL SPECIFICATION

P/N	PKG	QTY
AZ5825-01F-MS	DFN1006-2L	10000



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